

UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

SONY GROUP CORPORATION
Petitioner,

v.

VISIONX TECHNOLOGIES, LLC,
Patent Owner.

Case No. IPR2023-00296
Patent No. 7,867,808

**NOTICE OF FILING TRANSCRIPT OF MAY 24, 2023 CONFERENCE
CALL AND *SOTERA* STIPULATION**

LISTING OF EXHIBITS

Exhibit	Description
1001	U.S. Patent No. 7,867,808
1002	Prosecution History of U.S. Patent No. 7,867,808
1003	Declaration of Dr. L. Richard Carley
1004	Curriculum Vitae of Dr. L. Richard Carley
1005	U.S. Patent Application Pub. No. US 2006/0197007 A1 (“Iwabuchi”)
1006	Japanese Patent Application Pub. No. JP 2006-93587 A (“Maruyama”)
1007	Exhibit A to Declaration of Gordon Macpherson, T. Suga et al., “Surface activated bonding for new flip-chip and bumpless interconnect systems.” <i>52nd Electronic Components and Technology Conference</i> 2002, pp. 105-111, 2002 (“Suga”)
1008	PCT Application Pub. No. WO 2006/109937 A1 (“Lee”)
1009	Japanese Patent Application Publication No. JP 2006-303385 A (“Masagaki”)
1010	Japanese Patent Application Publication No. JP 2005-353996 (“Shiraiwa”)
1011	G. C. Bethea et al., “Long wavelength infrared 128×128 Al _x Ga _{1-x} As/GaAs quantum well infrared camera and imaging system,” <i>IEEE Transactions on Electron Devices</i> , vol. 40, no. 11, pp. 1957-1963, Nov. 1993 (“Bethea”)
1012	V. Dragoi and P. Lindner, “Plasma Activated Wafer Bonding of Silicon: In Situ and Ex Situ Processes.” <i>ECS Transactions</i> , vol. 3, no. 6, pp. 147-154, 2006 (“Dragoi”)
1013	Pages from S.M. Sze and Kwok K. Ng, <i>Physics of Semiconductor Devices</i> , John Wiley & Sons (3d ed. 2007) (“Sze”)
1014	A. Rogalski, “Infrared Detectors: Status and Trends.” <i>Progress in Quantum Electronics</i> , vol. 27, pp. 59-210, 2003 (“Rogalski”)
1015	U.S. Patent Application Pub. No. 2006/0043519 A1 (“Ezaki”)
1016	U.S. Patent Application Pub. No. 2003/0025160 A1 (“Suzuki”)
1017	Exhibit A1 to VisionX Infringement Contentions in <i>VisionX Technologies, LLC v. Sony Group Corp. et al.</i> , No. 2:22-cv-00178 (E.D. Tex.), served September 8, 2022 (“IC-A1”)

Exhibit	Description
1018	U.S. Patent No. 6,074,895 (“Dery”)
1019	K. W. Oh and C. H. Ahn, “Flip-chip packaging with micromachined conductive polymer bumps.” <i>Proceedings of 3rd International Conference on Adhesive Joining and Coating Technology in Electronics Manufacturing</i> 1998 (Cat. No.98EX180), pp. 224-228, 1998 (“Oh”)
1020	R. Balcerak and S. Horn, “Progress in the development of vertically integrated sensor arrays,” <i>Proc. SPIE 5783, Infrared Technology and Applications XXXI</i> , pp. 384-390, 2005 (“Balcerak”)
1021	B. Pain et al., “A Back-Illuminated Megapixel CMOS Image Sensor,” in <i>Proceedings IEEE Workshop on Charge-Coupled Devices and Advanced Image Sensors</i> , pp. 35-38, 2005 (“Pain2005”)
1022	U.S. Patent No. 6,762,473 B1 (“Gouscha”)
1023	Pages from <i>The Penguin Complete English Dictionary</i> (2006)
1024	U.S. District Court – Judicial Caseload Profile for the Eastern District of Texas, <i>available at</i> https://www.uscourts.gov/sites/default/files/fcms_na_distprofile0630.2022_0.pdf , p.35 (last visited September 30, 2022).
1025	U.S. Patent No. 5,903,021 (“Guidash”)
1026	Pages from <i>Wiley Electrical and Electronics Engineering Dictionary</i> , John Wiley & Sons, Inc. (2004)
1027	R.S. Patti, “Three-Dimensional Integrated Circuits and the Future of the System-on-Chip Designs.” <i>Proceedings of the IEEE</i> , vol. 94, no. 6, pp. 1214-1224, 2006 (“Patti”)
1028	U.S. Patent Pub. 2003/0038336 (“Mann”)
1029	U.S. Patent Application Publication No. US 2005/0161795 A1 (“Tong”)
1030	U.S. Patent No. 7,750,488 (“Patti488”)
1031	U.S. Patent Application Publication No. US 2006/0043438 A1 (“Holm”)
1032	PCT Application Pub. No. WO 2006/129762 A1 (“Iwabuchi-762”)
1033	Pages from C.Y. Chang and S.M. Sze, <i>ULSI Technology</i> . The McGraw-Hill Companies, Inc., 1996. (“ULSI”)

Exhibit	Description
1034	Pages from <i>The American Heritage Dictionary of the English Language</i> , Houghton Mifflin Company (4th ed. 2000).
1035	IPC-7351: Generic Requirements for Surface Mount Design and Land Pattern Standard (2005)
1036	INTERPOSER-TECH07: Lead-free to Tin/Lead BGA Interposer (Advanced Interconnections 2007)
1037	Pages from S.M. Sze, <i>Physics of Semiconductor Devices</i> (2d ed. 1981) (“Sze-1981”)
1038	Affidavit of Nathaniel E. Frank-White (“Frank-White Affidavit”)
1039	RESERVED
1040	A. El Gamal and H. Eltoukhy, H., “CMOS image sensors,” <i>IEEE Circuits and Devices Magazine</i> , 21(3), pp.6-20 (2005) (“Gamal”).
1041	Declaration of Gordon Macpherson with Exhibit A, R.S. Patti, “Three-Dimensional Integrated Circuits and the Future of the System-on-Chip Designs.” <i>Proceedings of the IEEE</i> , vol. 94, no. 6, pp. 1214-1224, 2006
1042	S. Tiwari et al., “Lateral p-i-n photodetectors with 18 GHz bandwidth at 1.3 μm wavelength and small bias voltages,” <i>International Electron Devices Meeting 1991</i> [Technical Digest], 1991, pp. 421-424 (“Tiwari”)
1043	U.S. Patent No. 6,984,816 B2 (“Holm-816”)
1044	Pages from S.M. Sze, <i>Semiconductor Devices: Physics and Technology</i> , John M. Wiley & Sons (2d ed. 2002) (“Sze-2002”).
1045	Mike Salib et. al, “Silicon Photonics,” <i>Intel Technology Journal</i> , volume 8, no. 2, pp. 143-160, 2004 (“Salib”)
1046	P. Lindner et al., “3D Interconnect Through Aligned Wafer Level Bonding,” in <i>52nd Electronic Components and Technology Conference 2002 (Cat. No. 02CH37345)</i> , pp. 1439-1443 (May 28, 2002) (“Lindner”)
1047	K. Keswick, R. L. German, M. Breen and R. Nolan, “Compliant bumps for adhesive flip-chip assembly,” <i>IEEE Transactions on Components, Packaging, and Manufacturing Technology: Part B</i> , vol. 18, no. 3, pp. 503-510, Aug. 1995 (“Keswick”)

Exhibit	Description
1048	J. H. Wu et al., “A high aspect-ratio silicon substrate-via technology and applications: through-wafer interconnects for power and ground and Faraday cages for SOC isolation,” <i>International Electron Devices Meeting 2000. Technical Digest. IEDM (Cat. No.00CH37138)</i> , 2000, pp. 477-480 (“Wu”)
1049	Transcript of May 24, 2023 Conference Call
1050	Letter from M. Rader to A. Alavi Re: <i>Sotera</i> Stipulations (May 16, 2023)

Pursuant to 37 CFR § 42.6(e)(4)(ii), and the Board's authorization during the May 24, 2023 Conference Call, Petitioner Sony Group Corporation herewith submits the following Exhibits:

<u>Exhibit</u>	<u>Description</u>
1049	Transcript of May 24, 2023 Conference Call
1050	Letter from M. Rader to A. Alavi Re: <i>Sotera</i> Stipulations (May 16, 2023)

Respectfully submitted,
Sony Group Corporation

Date: May 25, 2023

/Michael N. Rader/

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CERTIFICATE OF SERVICE UNDER 37 C.F.R. § 42.6 (E)(4)

I certify that on May 25, 2023, I will cause a copy of the foregoing document, including any exhibits filed therewith, to be served via electronic mail, as previously consented to by Patent Owner, upon the following:

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Masood Anjom
Steven Jugle

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